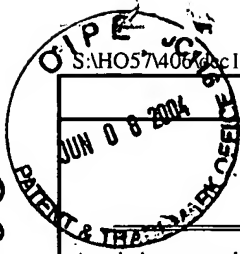


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SUPPLEMENTAL DECLARATION FOR PATENT APPLICATION SOLE OR JOINT

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention titled:

Methods of Treating Non-Sputtered Regions of PVD Target Constructions To Form Particle Traps, and PVD Target Constructions Comprising Projections Along A Non-Sputtered Region

the specification of which is attached hereto unless the following box is checked.

☒ was filed on July 9, 2003 as United States Application Number or PCT International Application
Number 10/614,806 and was amended on _____ (If Applicable).

I HEREBY STATE THAT I HAVE REVIEWED AND UNDERSTAND THE CONTENTS OF THE ABOVE-IDENTIFIED SPECIFICATION, INCLUDING THE CLAIMS.

I ACKNOWLEDGE THE DUTY TO DISCLOSE INFORMATION THAT IS MATERIAL TO THE PATENTABILITY OF THIS APPLICATION IN ACCORDANCE WITH TITLE 37, CODE OF FEDERAL REGULATIONS, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed and/or I hereby claim priority benefits under Title 35 U.S.C. §119 for any U.S. provisional application listed below:

Prior Foreign and/or U.S. Provisional Application(s)

(Number)	(Country)	(Day/Month/Year Filed)	Priority Claimed	
60/396,543	USA	July 16, 2002	X	
			Yes	No
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States applications listed below and, INsofar AS THE SUBJECT MATTER OF EACH OF THE CLAIMS OF THIS APPLICATION IS NOT DISCLOSED IN THE PRIOR UNITED STATES APPLICATION IN THE MANNER PROVIDED BY THE FIRST PARAGRAPH OF TITLE 35, UNITED STATES CODE, §112, I ACKNOWLEDGE THE DUTY TO DISCLOSE MATERIAL INFORMATION AS DEFINED IN TITLE 37, CODE OF FEDERAL REGULATIONS, §1.56(a) WHICH OCCURRED BETWEEN THE FILING DATE OF THE PRIOR APPLICATION AND THE NATIONAL OR PCT INTERNATIONAL FILING DATE OF THIS APPLICATION:

**

(Application Serial Number)	(Filing Date)	(STATUS: Patented, Pending, Abandoned)
(Application Serial Number)	(Filing Date)	(STATUS: Patented, Pending, Abandoned)

SEND CORRESPONDENCE TO: David G. Latwesen, Ph.D.
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SUPPLEMENTAL DECLARATION FOR PATENT APPLICATION—SOLE
OR JOINT (Cont'd.)

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

FULL NAME OF SOLE OR FIRST INVENTOR Jaeyoon Kim
INVENTOR'S SIGNATURE [Signature] Date 5/23/04
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FULL NAME OF SECOND JOINT INVENTOR _____
INVENTOR'S SIGNATURE _____ Date _____
RESIDENCE _____
CITIZENSHIP _____
POST OFFICE ADDRESS _____

FULL NAME OF THIRD JOINT INVENTOR _____
INVENTOR'S SIGNATURE _____ Date _____
RESIDENCE _____
CITIZENSHIP _____
POST OFFICE ADDRESS _____

FULL NAME OF FOURTH JOINT INVENTOR _____
INVENTOR'S SIGNATURE _____ Date _____
RESIDENCE _____
CITIZENSHIP _____
POST OFFICE ADDRESS _____

FULL NAME OF FIFTH JOINT INVENTOR _____
INVENTOR'S SIGNATURE _____ Date _____
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CITIZENSHIP _____
POST OFFICE ADDRESS _____

FULL NAME OF SIXTH JOINT INVENTOR _____
INVENTOR'S SIGNATURE _____ Date _____
RESIDENCE _____
CITIZENSHIP _____
POST OFFICE ADDRESS _____

FULL NAME OF SEVENTH JOINT INVENTOR _____
INVENTOR'S SIGNATURE _____ Date _____
RESIDENCE _____
CITIZENSHIP _____
POST OFFICE ADDRESS _____

